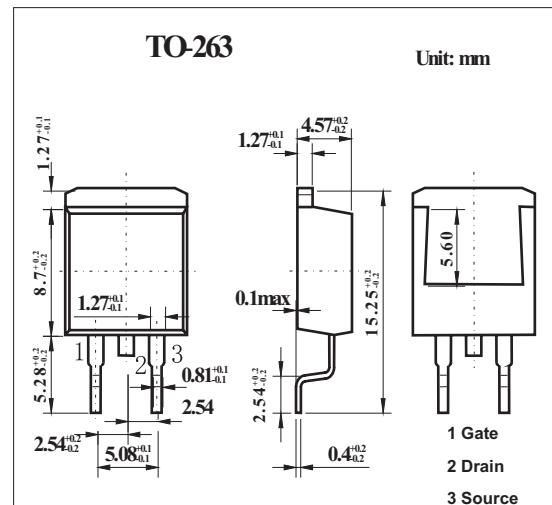


**N-channel enhancement mode MOSFET****2SK3731****■ Features**

- Low on-resistance, low Q<sub>g</sub>
- High avalanche resistance
- For high-speed switching

**■ Absolute Maximum Ratings Ta = 25°C**

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V <sub>DSS</sub>	230	V
Gate-source surrender voltage	V <sub>GSS</sub>	±30	V
Drain current	I <sub>D</sub>	20	A
Peak drain current	I <sub>DP</sub>	80	A
Avalanche energy capability *	E <sub>AS</sub>	668	mJ
Power dissipation	P <sub>D</sub>	50	W
Power dissipation Ta = 25°C		1.4	
Channel temperature	T <sub>ch</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

\*: L = 2.79 mH, I<sub>L</sub> = 20 A, V<sub>DD</sub> = 50 V, 1 pulse, T<sub>a</sub> = 25°C

**2SK3731**

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-source surrender voltage	V <sub>DSS</sub>	I <sub>D</sub> = 1 mA, V <sub>GS</sub> = 0	230			V
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0		4.0	V
Drain-source cutoff current	I <sub>DSS</sub>	V <sub>DS</sub> = 184 V, V <sub>GS</sub> = 0			10	μA
Gate-source cutoff current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0			±1	μA
Drain-source ON resistance	R <sub>DSS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		65	82	mΩ
Forward transfer admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 A	7	14		S
Short-circuit forward transfer capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0, f = 1 MHz		360		pF
Short-circuit output capacitance	C <sub>oss</sub>			394		pF
Reverse transfer capacitance	C <sub>rss</sub>			49		pF
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> ≈ 100 V, I <sub>D</sub> = 10 A R <sub>L</sub> = 10Ω, V <sub>GS</sub> = 10 V		31		ns
Rise time	T <sub>r</sub>			27		ns
Turn-off delay time	t <sub>d(off)</sub>			214		ns
Fall time	t <sub>f</sub>			47		ns
Diode foward voltage	V <sub>DSDF</sub>	I <sub>DR</sub> = 20 A, V <sub>GS</sub> = 0			21.5	V
Reverse recovery time	t <sub>rr</sub>	L = 230 μH, V <sub>DD</sub> = 100 V I <sub>DR</sub> = 10 A, di/dt = 100 A/μs		142		ns
Reverse recovery charge	Q <sub>rr</sub>			668		nC
Gate charge load	Q <sub>g</sub>	V <sub>DD</sub> = 100 V, I <sub>D</sub> = 10 A, V <sub>GS</sub> = 10 V		43		nC
Gate-source charge	Q <sub>gs</sub>			6.6		nC
Gate-drain charge	Q <sub>gd</sub>			16		nC
Thermal resistance (ch-c)	R <sub>th(ch-c)</sub>				2.5	°C/W
Thermal resistance (ch-a)	R <sub>th(ch-a)</sub>				89.2	°C/W